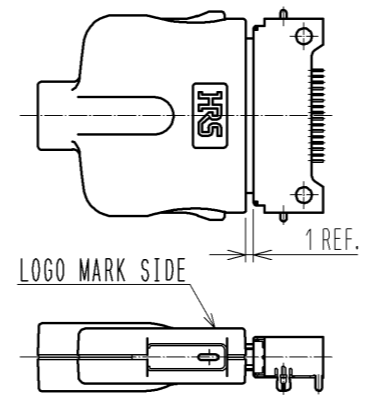
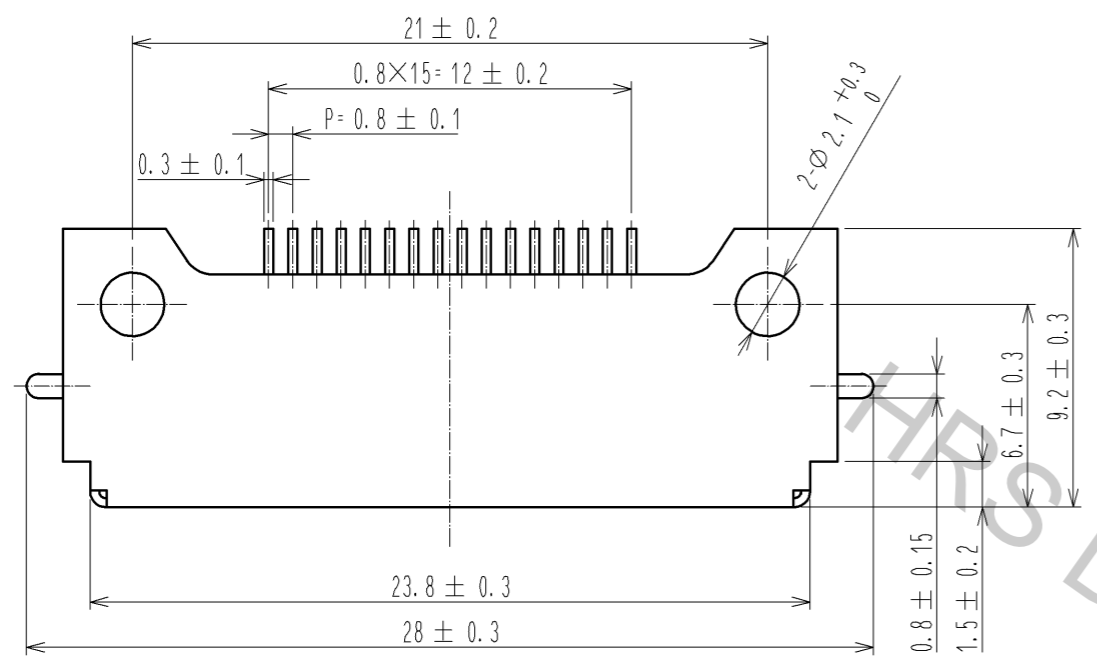
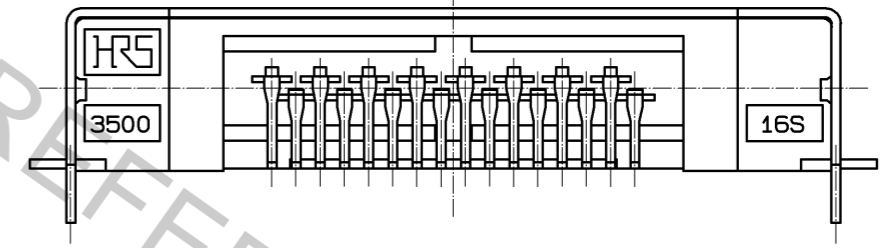
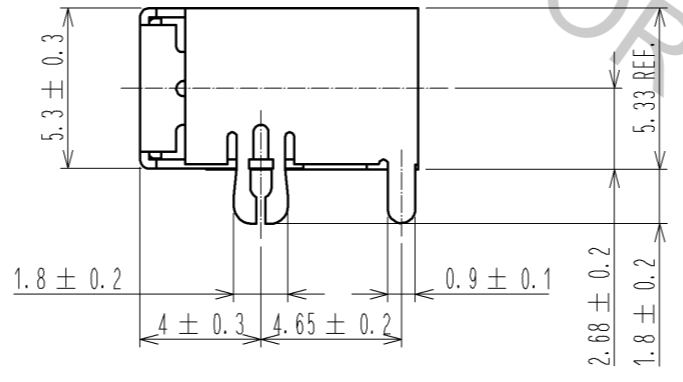
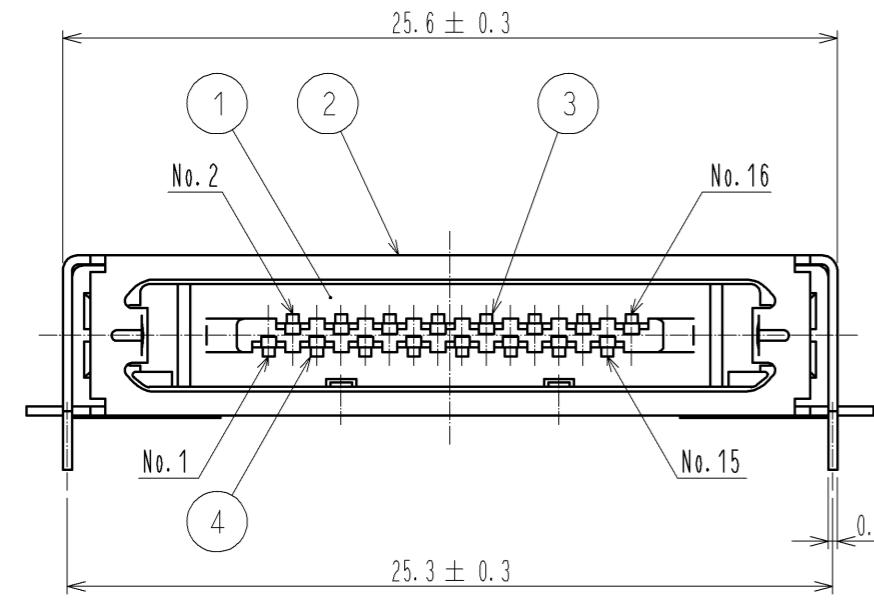
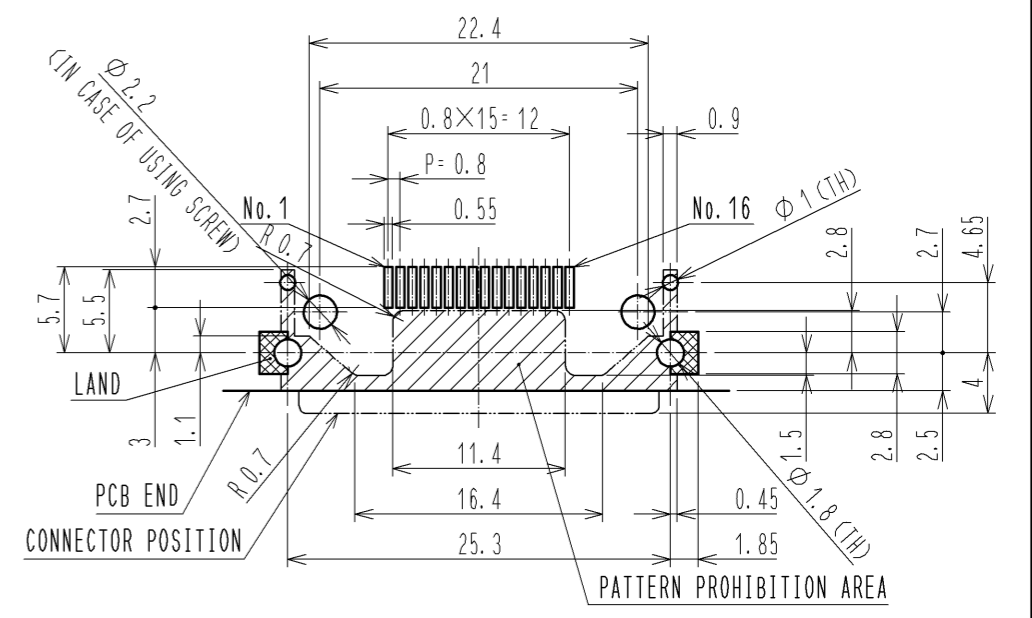
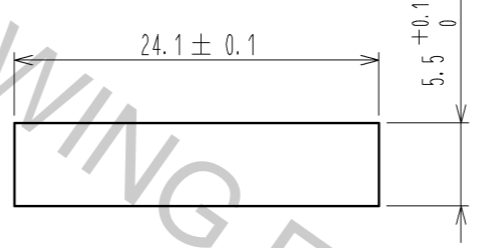


1 FIG-1 WITH MATED PLUG(1:1)

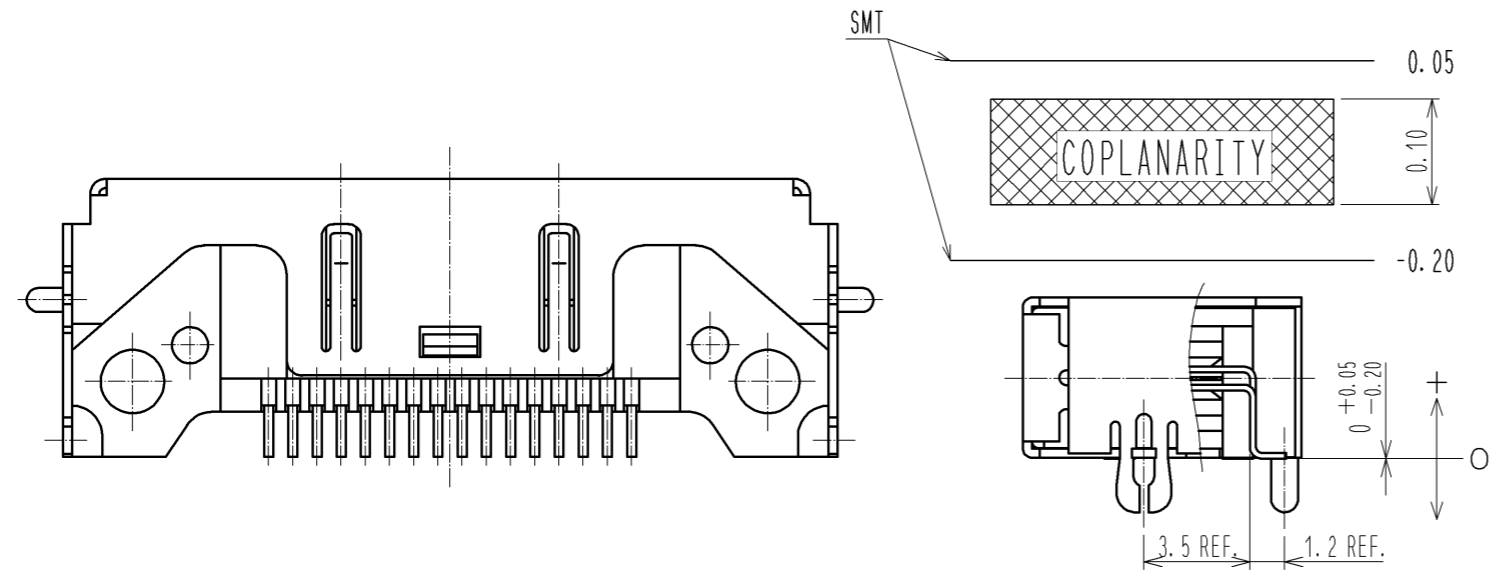
RECOMMENDED PC BOARD PATTERN
APPLICABLE PC BOARD t=0.8~1.6



PANEL CUTOUT(2:1)
(PANEL THICKNESS t=1.5 mm MAX)



2 FIG-2 SMT & COPLANARITY LEAD DIMENSIONS



NOTES
1 LOCK MARK ON PLUG IN MATED CONDISION IS AS SHOWN FIG-1.
2 SMT LEAD DIMENSION FOR CONTACT (REF No. ③, ④) SHALL BE AS SHOWN IN THE FIG.2

NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS
3	COPPER ALLOY	CONTACT(SURFACE) : GOLD PLATING 0.2µm MIN CONTACT(INTERMEDIATE) : PALLADIUM NICKEL PLATING 0.7µm MIN		4	COPPER ALLOY	CONTACT(SURFACE) : GOLD PLATING 0.2µm MIN CONTACT(INTERMEDIATE) : PALLADIUM NICKEL PLATING 0.7µm MIN	
2	STAINLESS STEEL	LEAD OVER : TIN REFLOW PLATING 1µm MIN LEAD UNDER : NICKEL PLATING 2µm MIN		1	POLYAMIDE	BLACK, UL94V-0	

UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	4:1	5	DIS-E-003883	MT. ITANO	YH. ENAMI	11.08.12

APPROVED	CHECKED	DESIGNED	DRAWN	DRAWING NO.	PART NO.	CODE NO.
HO. MIWA	YH. ENAMI	TU. TANIGUCHI	TU. TANIGUCHI	EDC3-120417-02	3560-16S(50)	CL235-0001-3-50